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(54) **SEMICONDUCTOR JOINING SUBSTRATE-USE TAPE WITH ADHESIVE AND COPPER-CLAD LAMINATE SHEET USING IT**

(57) The present invention relates to an adhesive-backed tape for semiconductors which is characterized in that it is composed of a laminate of an insulating film layer having the following characteristics (1) and (2) and at least one adhesive agent layer in the semi-cured state.

(1) The coefficient of linear expansion in the film transverse direction (TD) at 50-200°C is 17-30 ppm/°C

(2) The tensile modulus of elasticity is 6-12 GPa

By means of this construction the present invention can provide, on an industrial basis, an adhesive-backed tape suitable for producing semiconductor devices, together with copper-clad laminates, semiconductor connecting substrates and semiconductor devices employing said tape, and it enables the reliability of semiconductor devices for high density mounting to be enhanced.

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Figure 1

